

**IN THE SPECIFICATION:**

Please amend paragraph [0032] of the specification as follows:

[0032] The sub-mount 15 includes a mounting surface 15a that intersects the primary surface of the stem 9 and divides the space 13 into a first region 13a and a second region 13b. The lead terminal 17 locates in the first region 13a, while the lead terminals 19 and 21 locate in the ~~second~~ first region ~~13b~~ 13a in the space 13. The first extension member 5 has an L-shaped cross section having at least one elbow portion, and one side thereof is fixed to the lead terminal 17.

Please amend paragraph [0040] of the specification as follows:

[0040] The first extension member 5 is fixed to the lead terminal 17 with solder. The second extension member 6 is also fixed to the lead terminal 18 with solder. In the second extension member 6, a hollow is formed in its inner surface so as to fit the lead terminal thereto. The surplus solder spills into a groove 47 formed immediately by the hollow.

Please amend paragraph [0049] of the specification as follows:

[0049] In the optical module 1b, the lead terminal 17, different to ~~to~~ from the lead terminals 19 and ~~21~~ 20, is ~~not~~ positioned from where the thermoelectric device 7 can not be directly wire-bonded. However, by using the extension member 55, the lead terminal 17 provided in the first region 13a, behind the sub-mount 15, can be connected to the thermoelectric device 7 in the second region 13b of the space 13, in front of the sub-mount 15, with a bonding wire 57.

Please amend paragraph [0052] of the specification as follows:

[0052] The extension member 55 is fixed to the lead terminal 17 with solder 59. The other extension member 56 is also fixed to the lead terminal 18 with solder 61. ~~On the~~ The extension member 56 is provided with a hollow 59 for aligning the lead terminal 18 therein, and the lead terminal 18 is fixed in the hollow of the extension member 56 with solder 61. Excess solder may flow into grooves 61 formed in the inner surface of the extension member immediately by the hollow. An adhesive ~~in stead~~ instead of solder 59 and 61 may be used for fixing the extension member 55 and 56 to the lead terminal.

Please amend paragraph [0056] of the specification as follows:

[0056] ~~From~~ FIG. 9 to FIG. 12 show modifications of the extension member 5 and 6. Extension members in these embodiments shown in FIGS. ~~from 9 to 13~~ 12 also enable to electrically connect the lead terminal 17 disposed in the first region 13a, behind the sub-mount 15, with the thermoelectric device 7 disposed in the second region 13b, in front of the sub-mount. Next, these modified extension members will be described in detail.